Surface Mountable PTC Resettable Fuse

Specifications:

RoHS Compliant

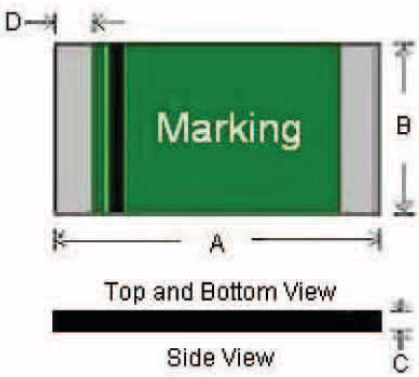
Applications : All high-density boards
Product Features : Small surface mountable, Solid state, Faster time to trip than standard SMD devices, Lower resistance than standard SMD devices
Temperature Range : -40°C to 85°C

Electrical Characteristics (23°C)

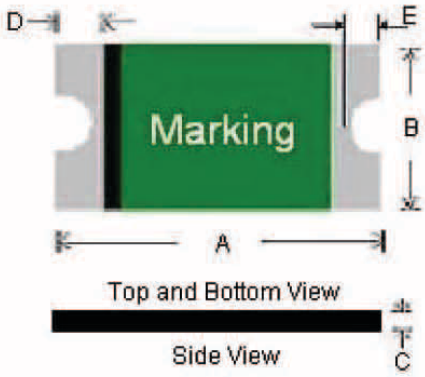
Hold Current	Trip Current	Rated Voltage	Maximum Current	Typical Power	Max Time to Trip		Resistance		Part Number
					Current	Time	R Minimum	R1 Maximum	
I_H, A	I_T, A	V Maximum, V dc	I Maximum, A	Pd, W	Amp	Sec	ohms	ohms	
0.20	0.40	30	10	0.4	8.00	0.10	0.600	2.500	MC36207
0.35	0.75	16	40				0.300	1.200	MC36211
0.75	1.50	6	100	0.6		0.20	0.090	0.290	MC36216
1.00	1.80					0.30	0.055	0.210	MC36221
1.10	2.20			0.8			0.040	0.180	MC36222
1.50	3.00					1.00	0.030	0.120	MC36229

I_H =Hold current-maximum current at which the device will not trip at 23°C still air.
I_T =Trip current-minimum current at which the device will always trip at 23°C still air.
V_{MAX} =Maximum voltage device can withstand without damage at its rated current. (I maximum)
I_{MAX} =Maximum fault current device can withstand without damage at rated voltage (V maximum).
Pd =Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.
R_{MIN} =Minimum device resistance at 23°C prior to tripping.
$R1_{MAX}$ =Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.
Termination pad characteristics
Termination pad materials: Pure Tin

FSMD Product Dimensions (Millimetres)



MC36207
MC36211

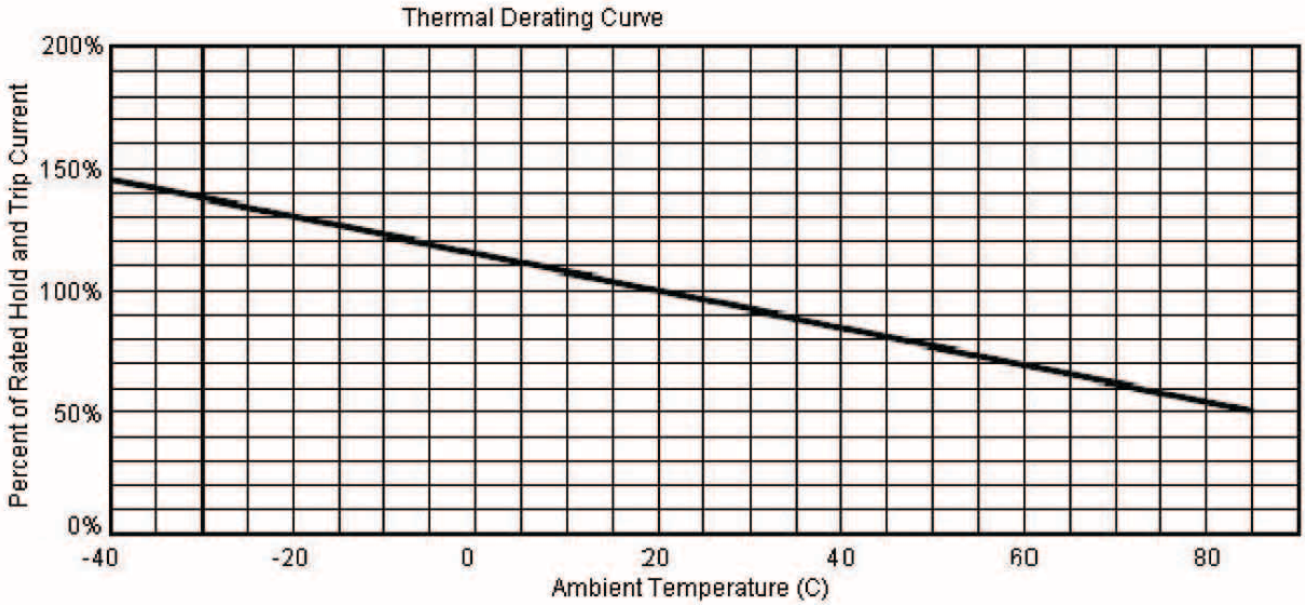


MC36216
MC36221
MC36222
MC36229

Specification Table

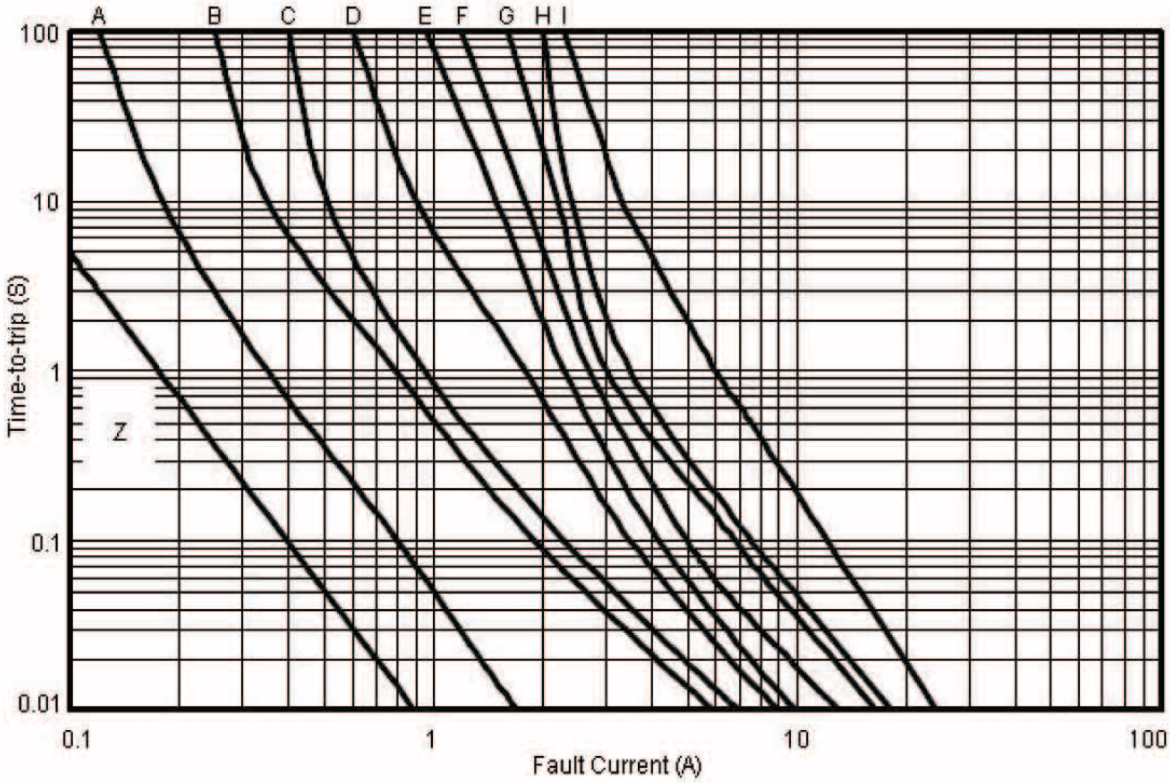
A		B		C		D		E		Part Number
Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	Minimum	Maximum	
3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	—	—	MC36207
										MC36211
					1.25	0.25		0.10	0.45	MC36216
					1.00					MC36221
										MC36222
				0.80	1.40					MC36229

Thermal Derating Curve



Typical Time-To-Trip at 23°C

B = MC36207
C = MC36211
E = MC36216
F = MC36221
G = MC36222
H = MC36229

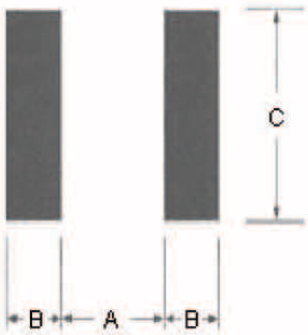


Material Specification

Terminal pad material : Pure Tin
Soldering characteristics :Meets EIA specification RS 186-9E, ANSI/J-std-002 Category 3

Pad Layouts, Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each FSMD1812 device



Device	A Nominal	B Nominal	C Nominal
All 1206 Series	2.00	1.00	1.90

Dimensions: millimetres

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/second maximum
Preheat : Temperature Minimum (Tsmin) Temperature Maximum (Tsmax) Time (tsmin to tsmax)	 150 °C 200 °C 60-180 seconds
Time maintained above: Temperature(TL) Time (tL)	 217 °C 60-150 seconds
Peak/Classification Temperature(Tp)	260 °C
Time within 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate :	6 °C/second maximum
Time 25 °C to Peak Temperature :	8 minutes maximum

Note 1: All temperatures refer to of the package, measured on the package body surface.

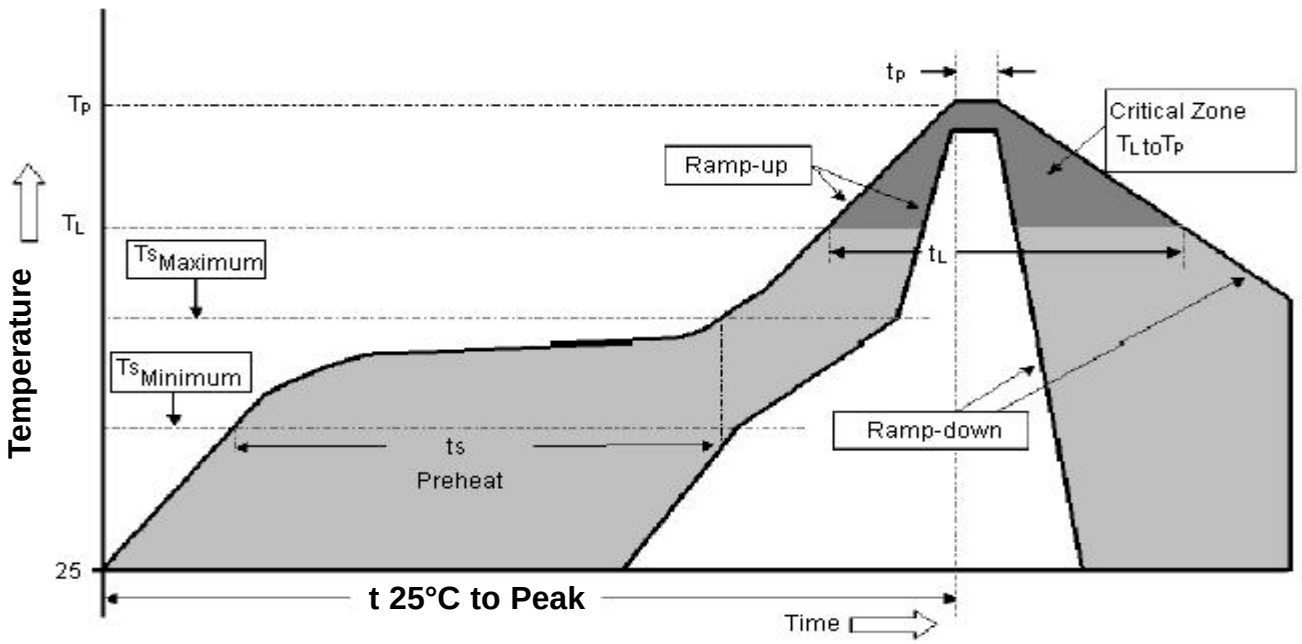
Solder reflow

Due to “Lead Free” nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

1. Recommended max past thickness > 0.25mm.
2. Devices can be cleaned using standard methods and aqueous solvent.
3. Rework use standard industry practices.
4. Storage Envorinment : < 30°C / 60%RH

Caution:

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.



Part Number Table

Description	Part Number
Surface Mountable PTC Resettable Fuse	MC36207
Surface Mountable PTC Resettable Fuse	MC36211
Surface Mountable PTC Resettable Fuse	MC36216
Surface Mountable PTC Resettable Fuse	MC36221
Surface Mountable PTC Resettable Fuse	MC36222
Surface Mountable PTC Resettable Fuse	MC36229